

On-going studies on diminishing the acceptor removal effect by tuning the charge state of Boron containing defects in p-type irradiated PAD samples

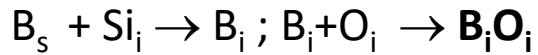
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June, 2024

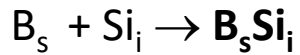
The *bistable behavior* of a Boron Containing Donor (BCD) related to acceptor removal (AR) effect observed in high resistivity PAD and LGAD samples^{1,2}

Possible assignments of BCD:

1) B_iO_i formed via the reactions¹⁻³



2) B_sSi_i formed via the reaction^{4,5}



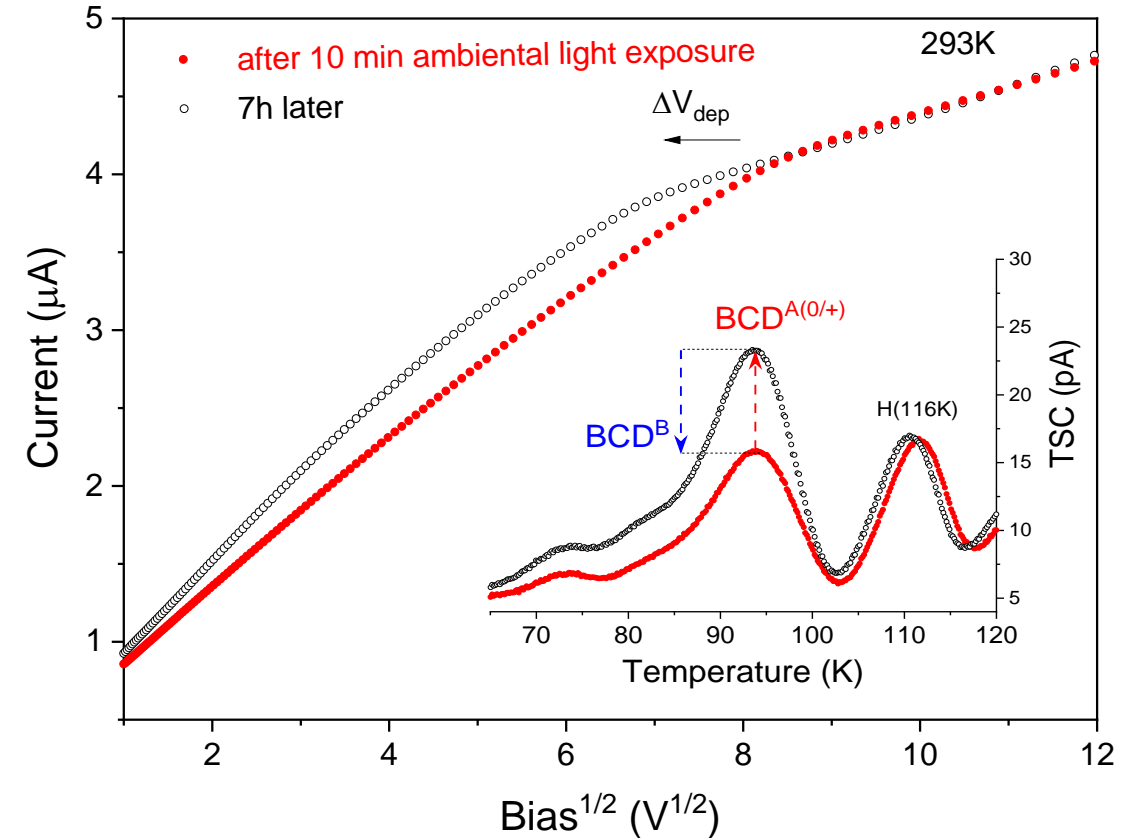
both are deactivating the acceptor dopant (Boron substitutional)

Configuration A- the ground state in eq. conditions, with a donor level at $E_c - 0.28$ eV, **contributing with positive charge to N_{eff}** - maximizing the AR effect

Configuration B- the ground state in non-eq. conditions (excess of carriers), **not electrically active** and is indirectly observed via the variations in the A configuration –**minimize AR**

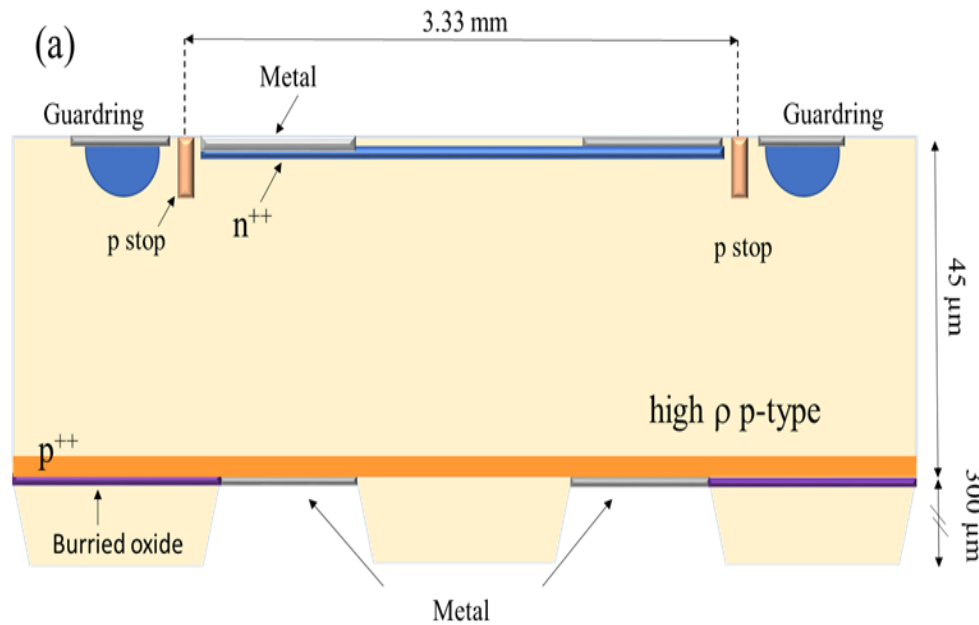
BCD^A trapping parameters:

$$E_t = 0.28\text{eV} - \delta E(F); \sigma_n = 1.05 \times 10^{-14} \text{ cm}^2; \sigma_p = 2.5 \times 10^{-20} \text{ cm}^2$$

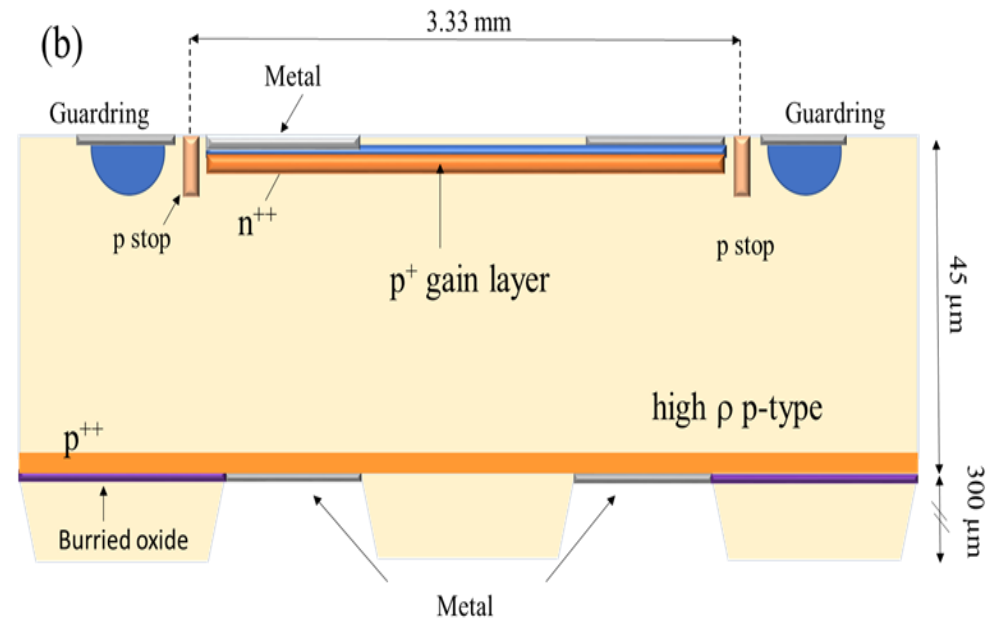


- 1). C. Besleaga, et al, Bistability of the BiO_i complex and its implications on evaluating the acceptor removal process in p-type silicon, Nucl. Instrum. Methods Phys. Res. A 2021, 1017, 165809. DOI: [10.1016/j.nima.2021.165809](https://doi.org/10.1016/j.nima.2021.165809); 2). A. Nitescu et al. "Bistable Boron-Related Defect Associated with the Acceptor Removal Process in Irradiated p-Type Silicon—Electronic Properties of Configurational Transformations". Sensors 2023, 23, 5725. <https://doi.org/10.3390/s23125725>; 3). Chuan Liao et al, IEEE TRANSACTIONS ON NUCLEAR SCIENCE 2022, 69 (3), pp.576-586, DOI: [10.1109/TNS.2022.3148030](https://doi.org/10.1109/TNS.2022.3148030); 4). Möller, C.; Lauer, K. Light-induced degradation in indium-doped silicon. Phys. Status Solidi RRL 2013, 7, 461. DOI: [/10.1002/pssr.201307165](https://doi.org/10.1002/pssr.201307165); 5). K. Lauer, et al, Activation energies of the In_s-Si_i defect transitions obtained by carrier lifetime measurements. Phys. Status Solidi C 2017, 14, 1600033. DOI: [/10.1002/pssc.201600033](https://doi.org/10.1002/pssc.201600033)

High resistivity PAD and LGAD samples



W5-LGB-72P
 $\rho = 12 \text{ k}\Omega\text{cm}$
 $\phi = 1E14 \text{ n/cm}^2$
Guardring grounded

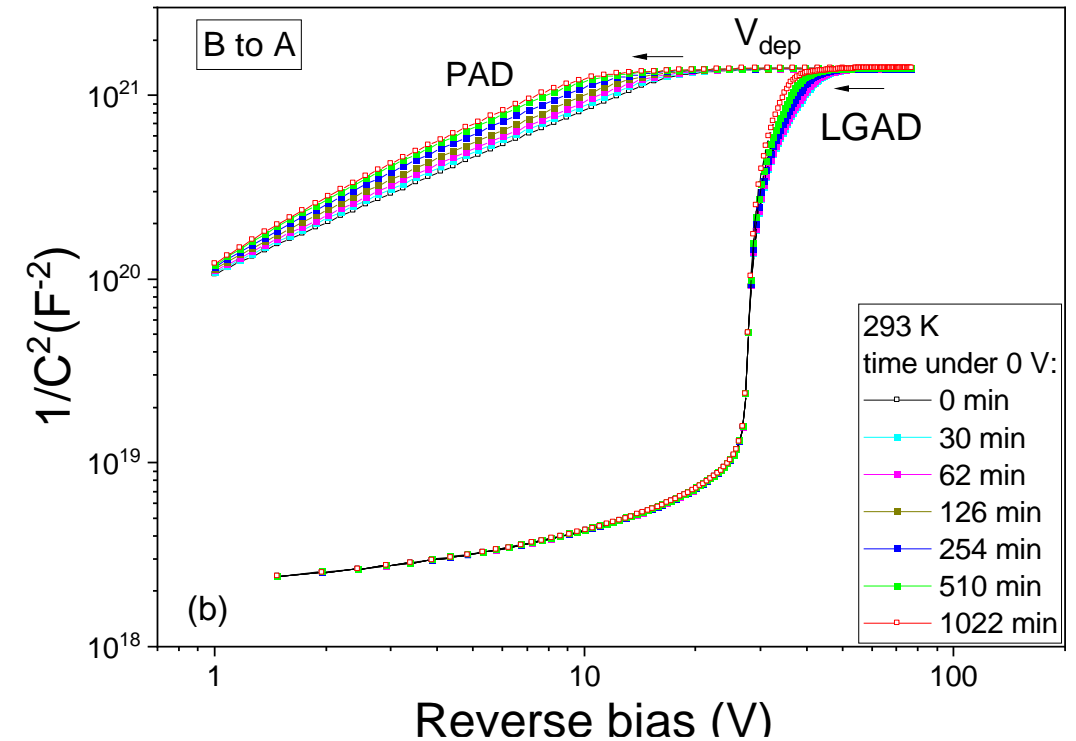
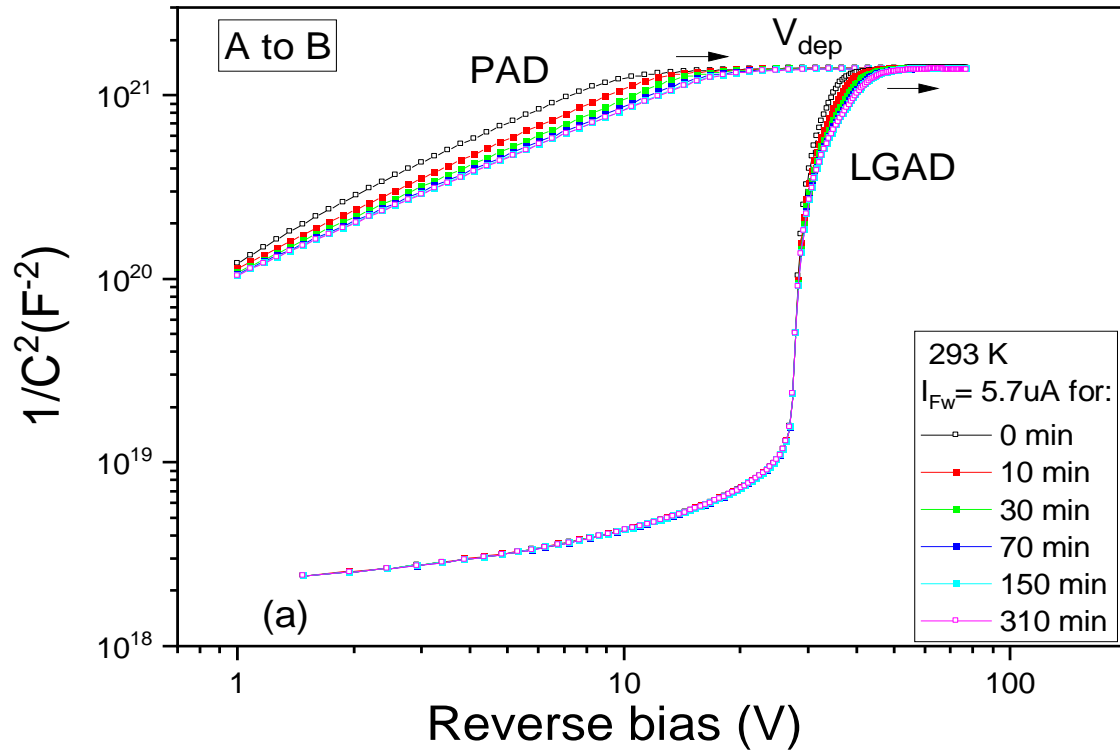


W3-LGB-71
 $\rho = 12 \text{ k}\Omega\text{cm}$
 $\phi = 1E14 \text{ n/cm}^2$
Guardring grounded

Reversible switch between the two charge configurations of BCD

As seen in CV measurements^{1,2}

12 kohm·cm PAD and LGAD irradiated with 10^{14} 1MeVn/cm², long time annealed at 80 °C



A to B:

- by producing an excess of carriers in samples
- Leads to an increase in V_{dep} (with ~ 6.3 V)

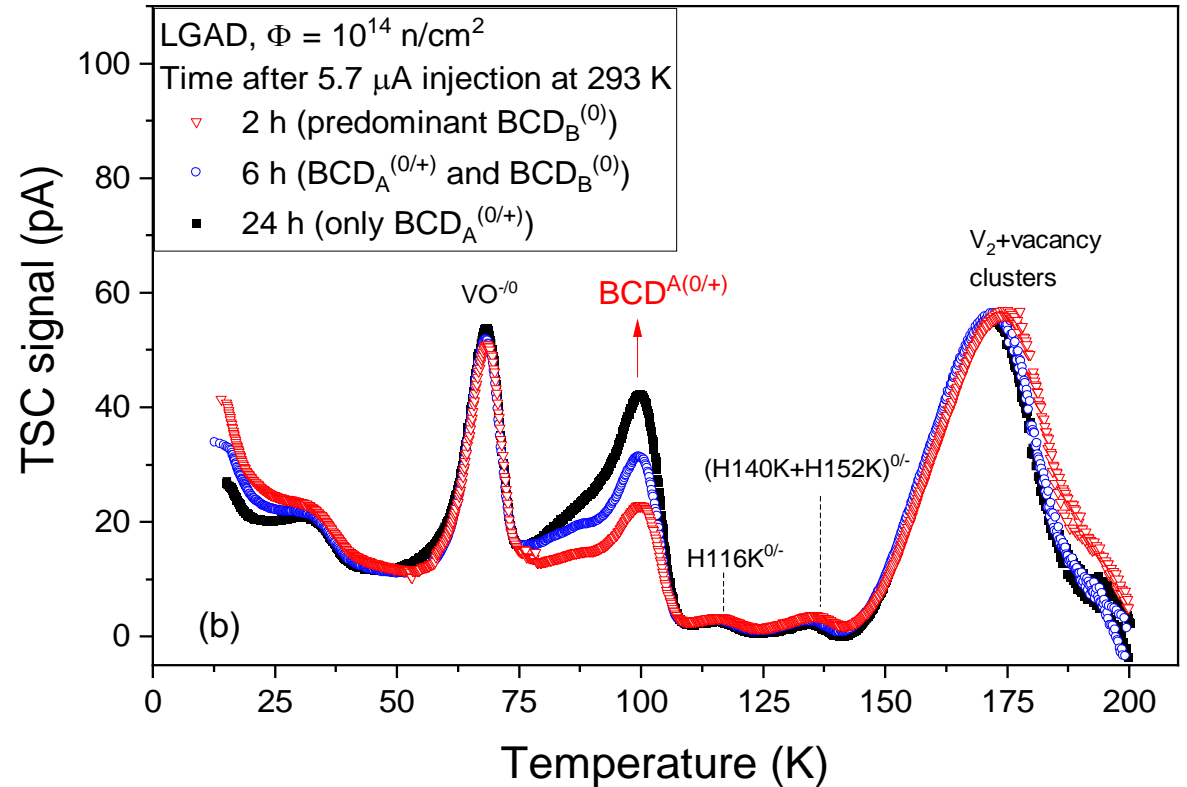
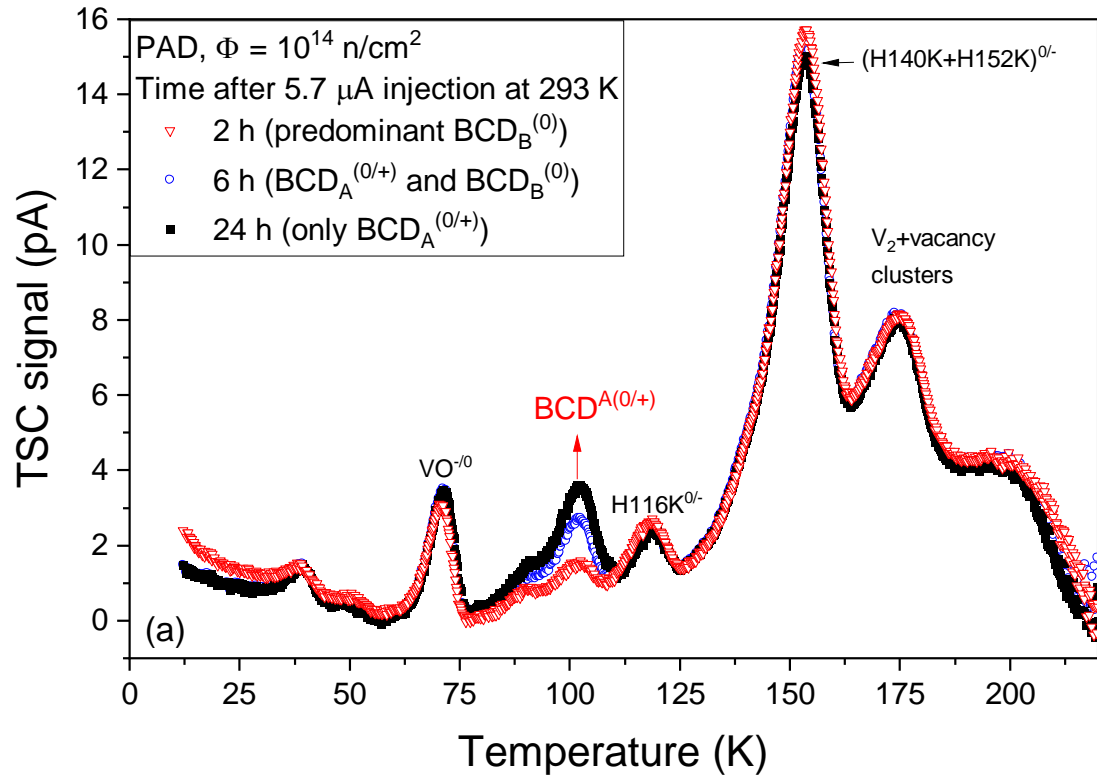
B to A:

- by keeping the sample in the dark
- V_{dep} returns back to its equilibrium value

Reversible switch between the two charge configurations of BCD

As seen in TSC measurements^{1,2} - possible only via monitoring the concentration of BCD^A

12 kohm·cm PAD and LGAD irradiated with 10^{14} 1MeVn/cm²

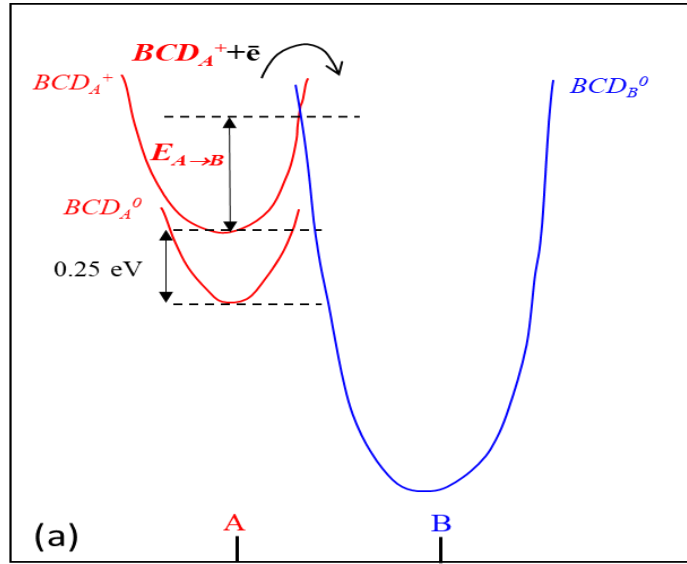
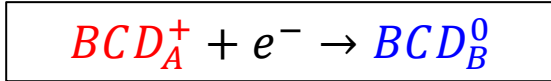


The changes from $A \rightarrow B$ is due to the excess of charge carriers. This excess of charge carriers can be stimulated through different methods:

- Thermal treatments (at $T < 80^\circ C$)
- FW current injection
- Light exposure

BCD defect kinetics, as seen in high resistivity samples²

A → B

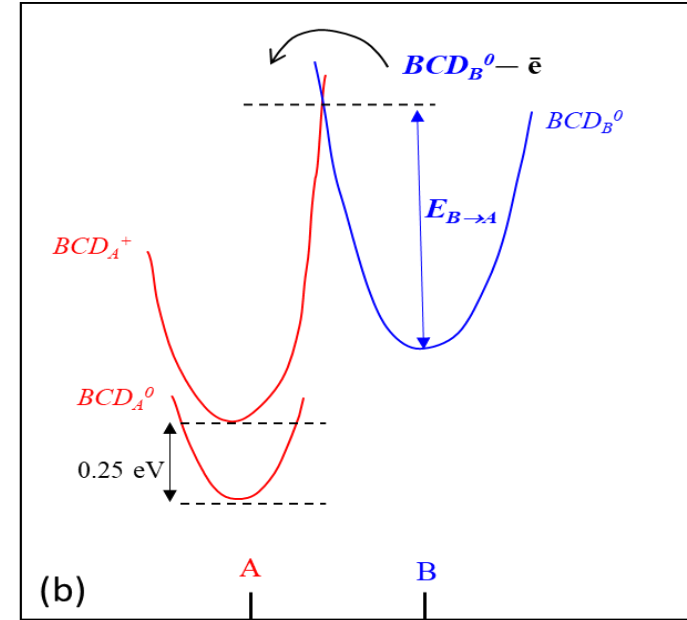
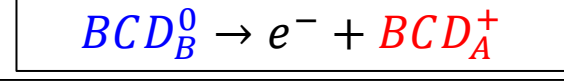


$$E_{A \rightarrow B} = 0.363 \text{ eV}$$

$$k_{A \rightarrow B} \cong 10^3 * \exp\left(-\frac{0.363 \text{ eV}}{k_B T}\right)$$

fast process, **diminishing** the AR effect
(recovers part of the removed acceptors)

B → A

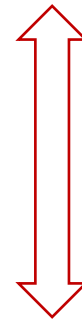


$$E_{B \rightarrow A} = 0.94 \text{ eV}$$

$$k_{B \rightarrow A} \cong 1.2 * 10^{12} * \exp\left(-\frac{0.94 \text{ eV}}{k_B T}\right)$$

- **slow returning process, enhancing the AR effect (maximize the AR effect)**
- below 273 K the B state frozen

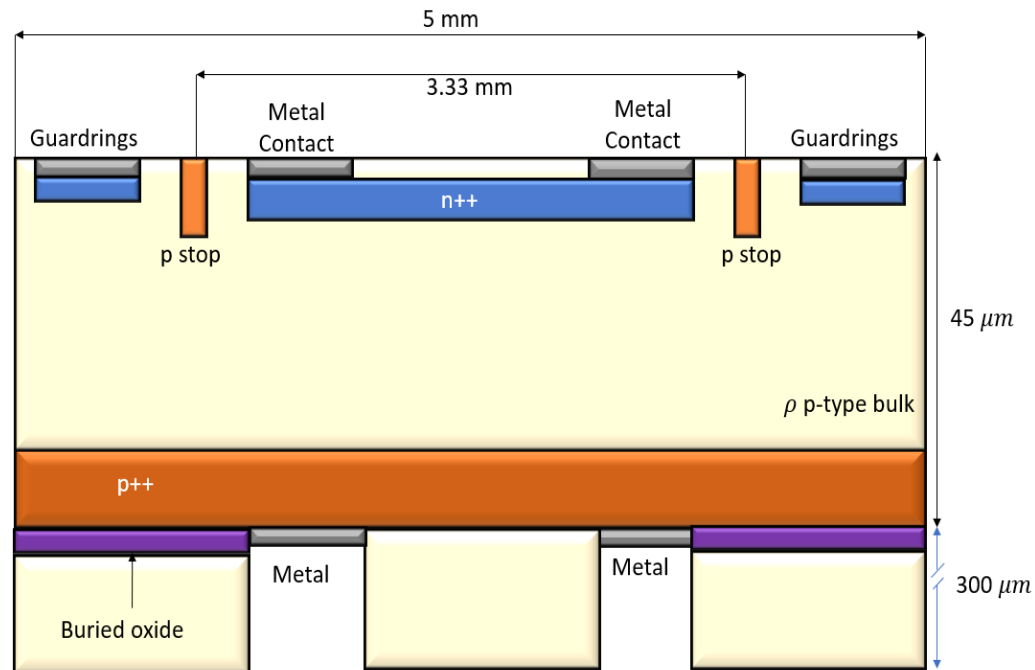
$$g_B = 2 \times g_{BCD}^A + g_{BCD}^B$$



It is possible to tune the defects configurations for **minimizing the AR effect by switching the defect from BCD_A^+ to BCD_B^0** – diminishing the contribution of **A** state which is accounted twice in g_B !

- ***Does BCD's bistability manifest also in samples of lower resistivity ?***

Samples of different resistivity (annealed 120min@60°C)



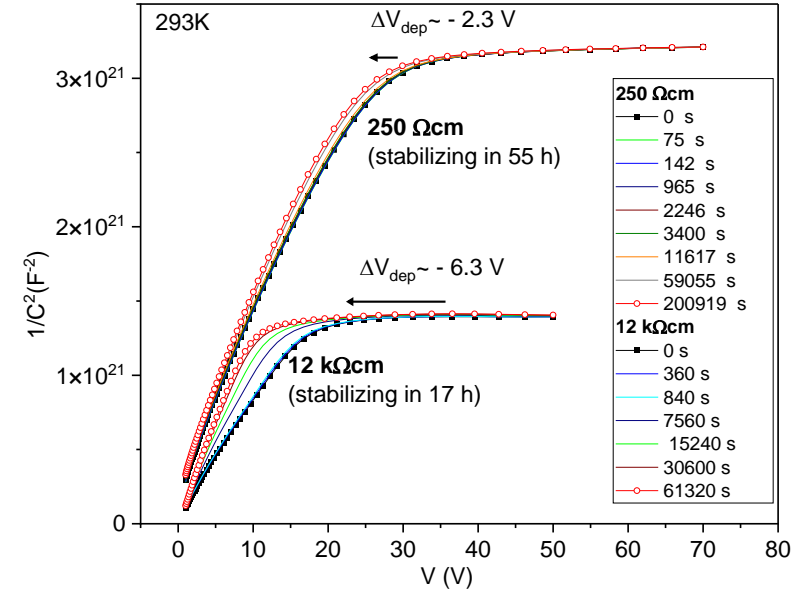
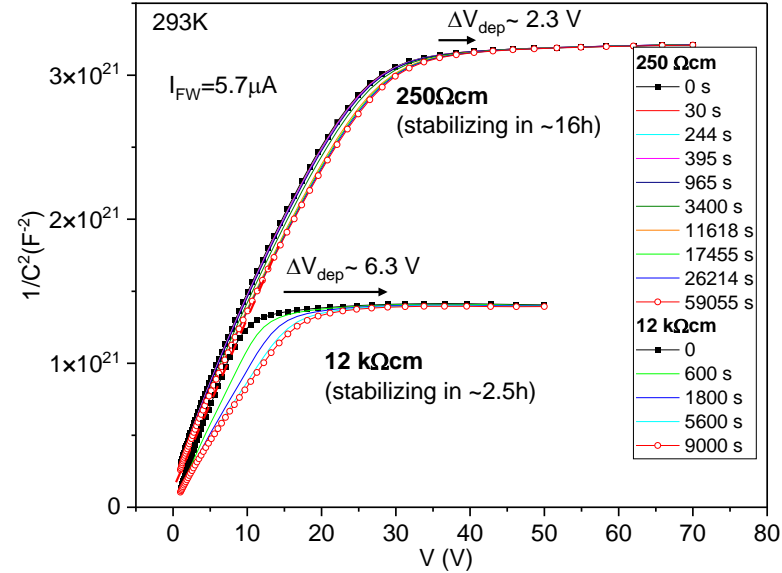
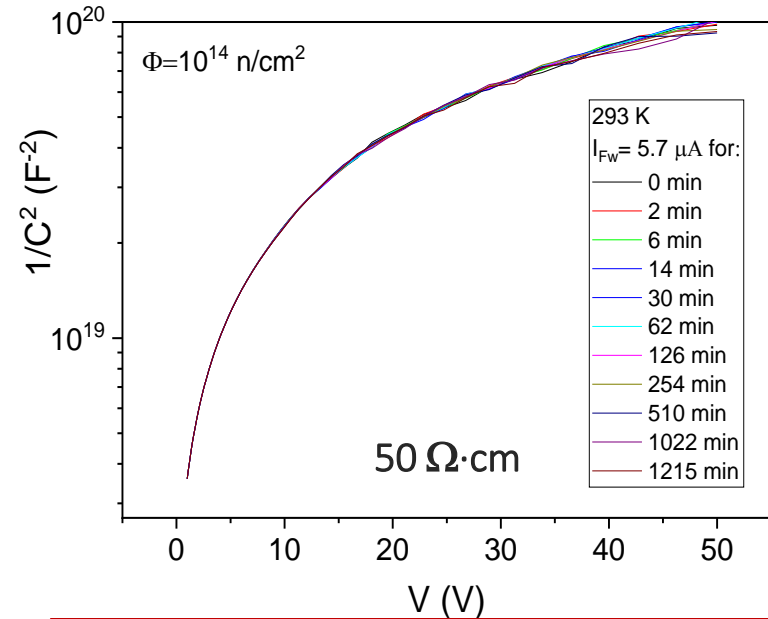
EPI-02-50-65
 $\rho = 50 \Omega\text{cm}$
 $\phi = 1E14 \text{ n/cm}^2$

EPI-09-50-DS-88
EPI-09-50-DS-89
 $\rho = 250 \Omega\text{cm}$
 $\phi = 1E14 \text{ n/cm}^2$

Results on the samples of different resistivity (50 $\Omega\cdot\text{cm}$, 250 $\Omega\cdot\text{cm}$ and 12 k $\Omega\cdot\text{cm}$), $\phi = 1E14 \text{ n/cm}^2$

A \rightarrow B (injecting small Fw current at 293 K, fast process)

B \rightarrow A (in dark under 0V, slow process)



A to B:

- For **12k $\Omega\cdot\text{cm}$** : $\Delta V_{\text{dep}} \sim 6.3 \text{ V} \rightarrow$ acceptor reactivation of $3.3 \times 10^{12} \text{ cm}^{-3}$
- For **250 $\Omega\cdot\text{cm}$** : $\Delta V_{\text{dep}} \sim 2.3 \text{ V} \rightarrow$ acceptor reactivation of $1.2 \times 10^{12} \text{ cm}^{-3}$
- For **50 $\Omega\cdot\text{cm}$** : $\Delta V_{\text{dep}} = 0$, no reactivation of acceptors

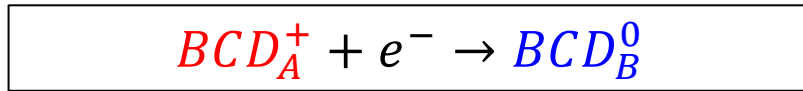
B to A (after removing the Fw injection):

- Happen very slowly for $T > 253\text{K}$
- At 253K, the B state remain frozen !
(the acceptor removal effect remains reduced to its minimum)

The efficiency of switching the defect' charge configuration is increasing with the sample' resistivity

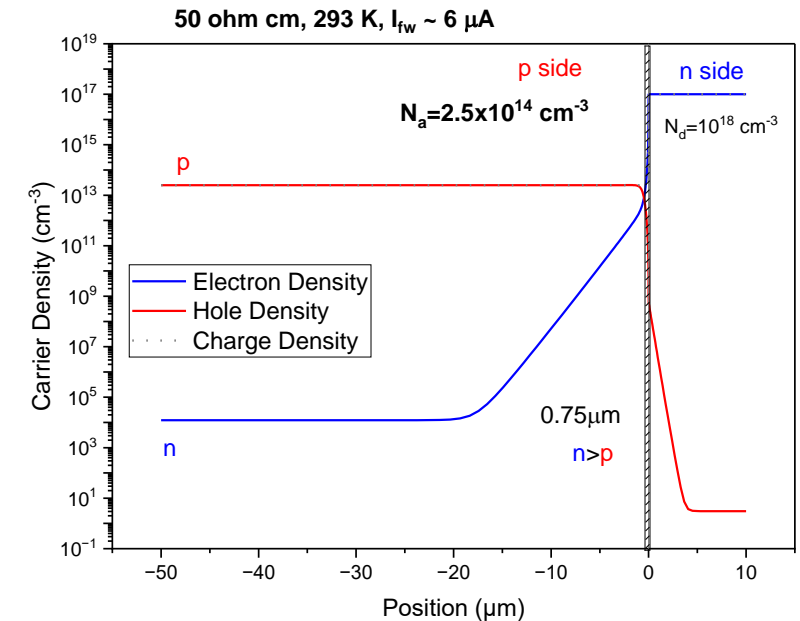
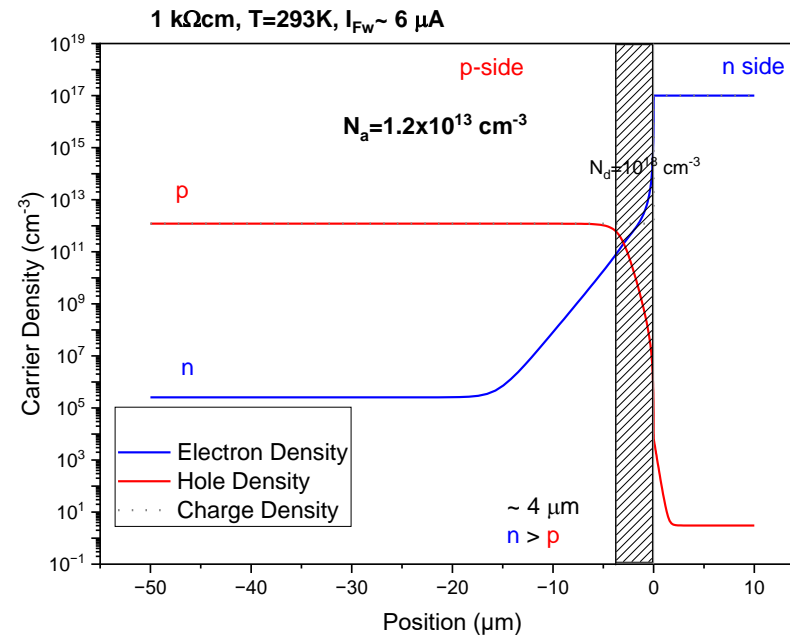
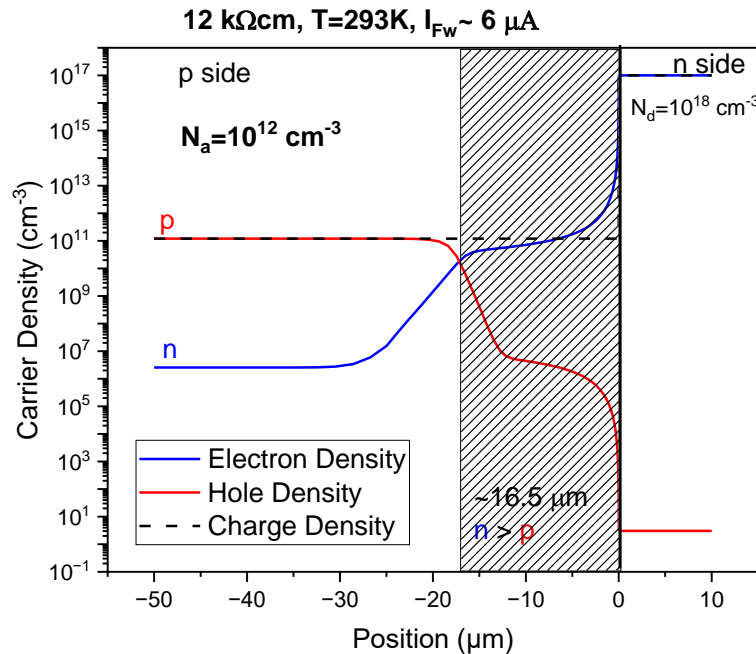
- Why can be reactivated more acceptors in high resistivity than in low resistivity samples after the same small Fw current injection ?

A → B



$$E_{A \rightarrow B} = 0.363 \text{ eV}$$

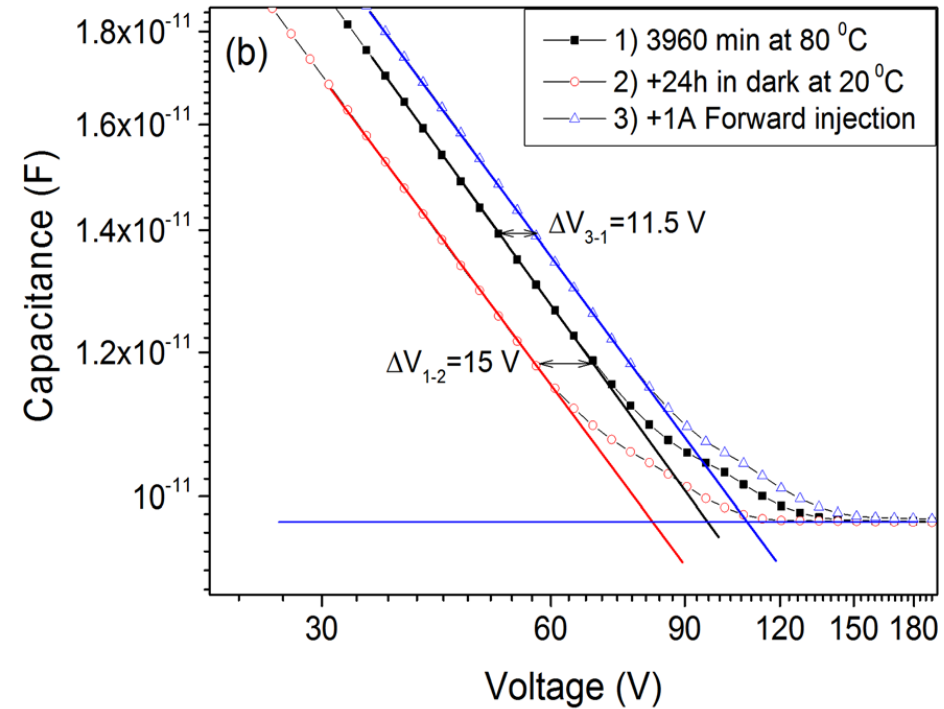
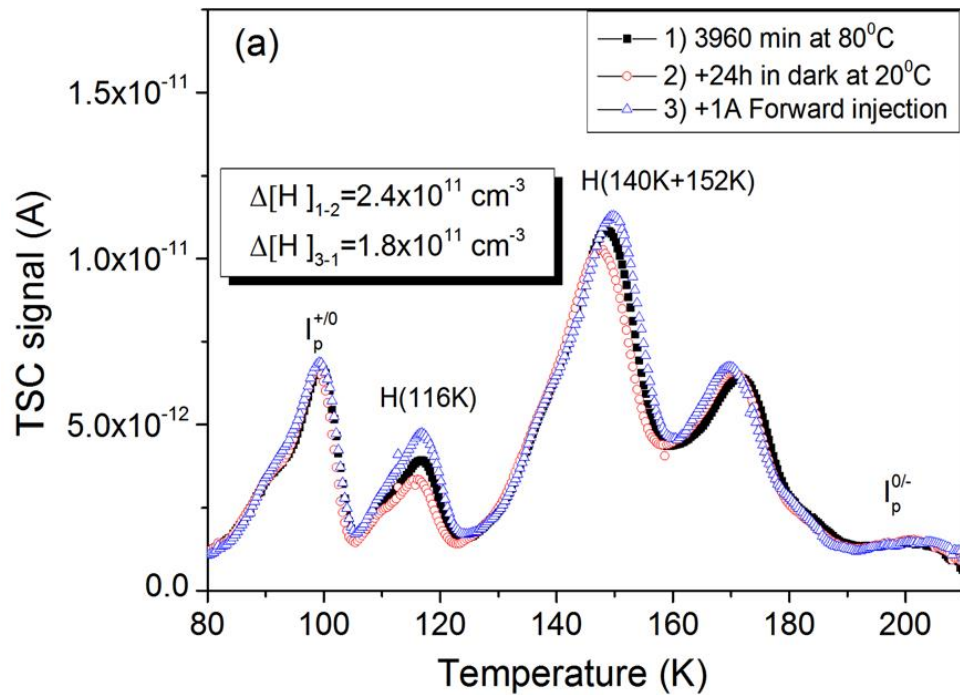
$$k_{A \rightarrow B} \cong 10^3 * \exp\left(-\frac{0.363 \text{ eV}}{k_B T}\right)$$



The volume in which the density of free electrons is larger than that of holes increases with resistivity → the change of the BCD configuration from A to B (with some recovery of acceptors) after small Fw current injection is observed in high resistivity diodes.

• Are other bistable effects that may overlap to that of BCD ?

- yes, we know that the cluster related hole traps, responsible for the magnitude of reverse annealing in n-type Silicon, show a bistable behavior after high irradiation levels



R. Radu et al, J. Appl. Phys. 117, 164503 (2015)

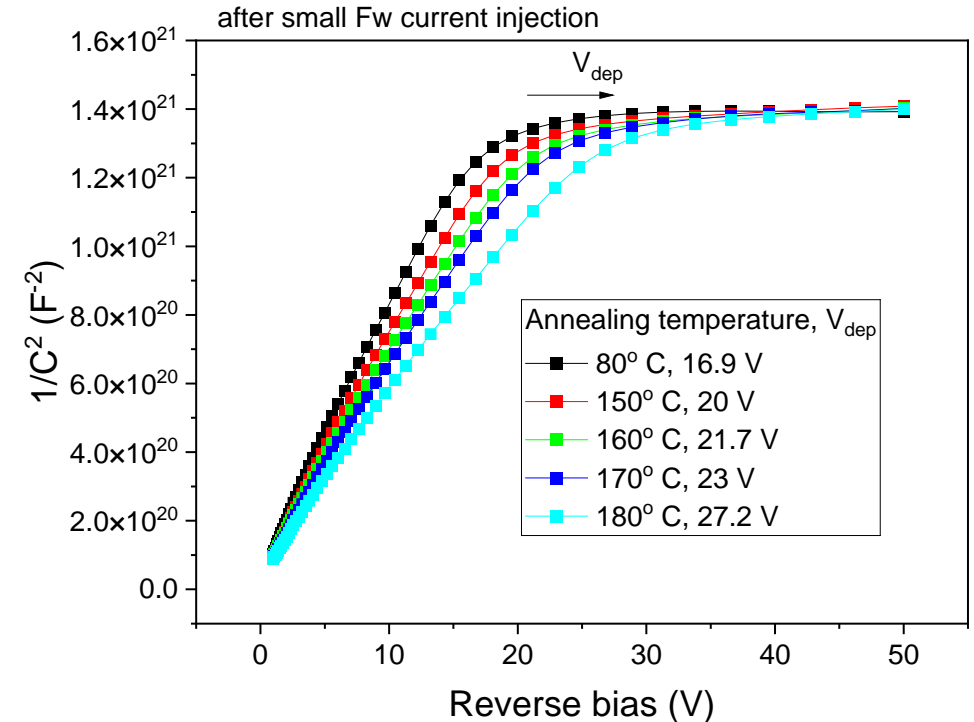
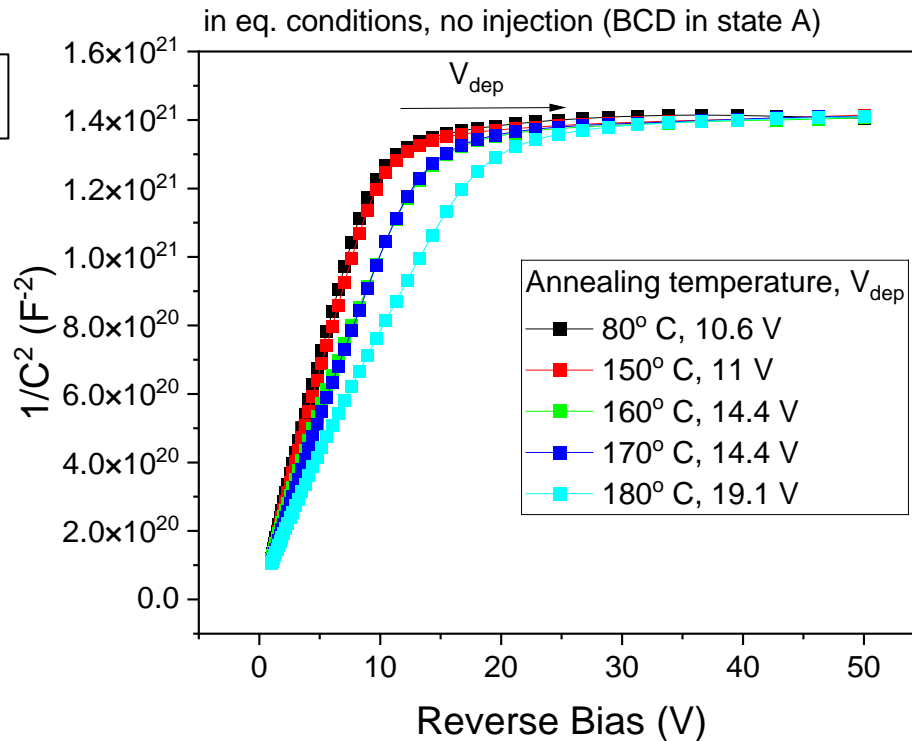
Bistability of H(116 K), H(140 K), and H(152 K) defects and corresponding change in V_{dep} of a 300 μm thick STFZ diode irradiated with 27MeV electrons, $\Phi=10^{14} \text{ cm}^{-2}$ (type inverted) and annealed for 3960 min at 80 C: (a) TSC spectra; (b) C-V curves measured with a frequency of 10 kHz and 0.5V small ac signal;

As acceptors in the lower part of the gap the impact of H116K, H140K and H152K clusters on N_{eff} in p-type Silicon is opposite to that of BCD (donors in the upper part of the gap)

Annealing studies on $12\text{ k}\Omega\text{cm}$ PAD samples

We know that: - BCD defect dissociates in ($160^\circ\text{C} - 200^\circ\text{C}$) the temperature interval⁴
- H116K, H140K and H152K continue forming

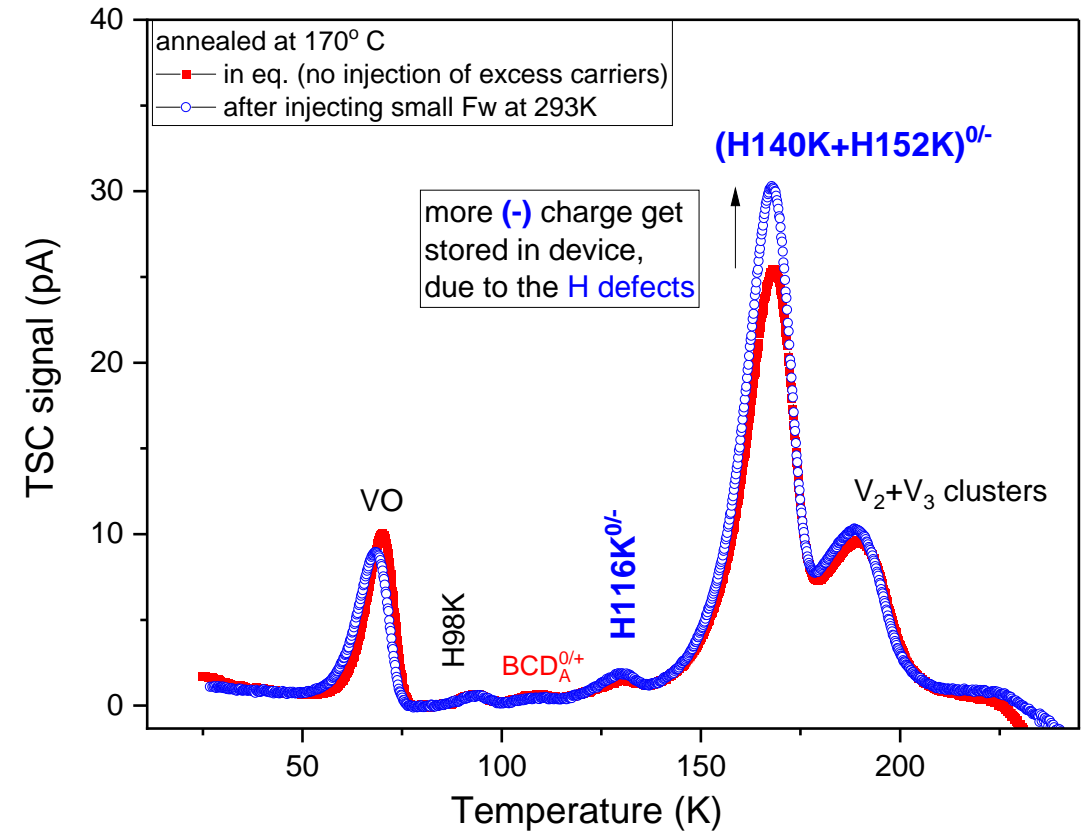
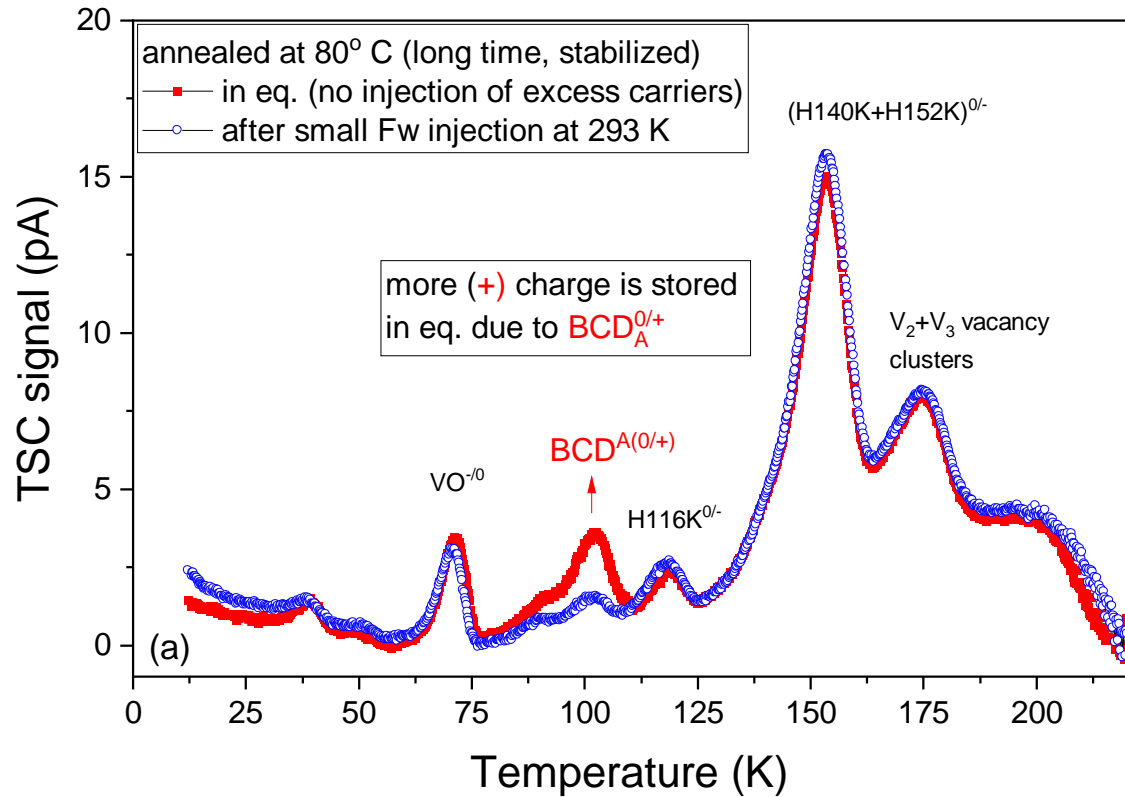
CVs at 293 K



- During annealing, V_{dep} increases both, in eq. conditions and after small Fw injection
- While after annealing at 180°C an increase of $\sim 10\text{ V}$ in V_{dep} is measured, only a 6.3 V can be attributed to the dissociation of BCD, the rest is due to the H116K, H140K and H152K defects

Annealing studies on 12 kΩcm PAD samples

TSC experiments



- before the annealing the observed bistability is mainly due to BCD ($\Delta V_{dep} \sim 6.3$ V)
- after annealing at 180°C (where BCD signal vanishes) the amount of *H-type cluster defects increases twice* becoming the main source for the observed bistabilities ($\Delta V_{dep} \sim 4$ V)

Conclusions

- The acceptor removal effect can be minimized by switching the BCD from its stable, positively charged configuration **A**, to the neutral one **B**. Such a process is very efficient in high resistivity p-type Silicon.
- The more favorable **B** state can be achieved by small injection of carriers. The **B** state froze-in at 253K.
- Isochronal annealing at temperatures below 200 °C reveals that also **the cluster defects, acceptors in the lower part of the gap, manifest bistability** – small Fw injections increase the negative charge stored on these defects and so, their bistability can also be used to minimize the acceptor removal effect.
- The study on *H116K*, *H140K* and *H152K* clusters just started and will continue for establishing the kinetics behind bistability and whether the more favourable configuration with respect to AR effect can be frozen-in

Thank you for your attention!